

Technical Support for Wire Bonding

お客様のために、地球環境のために。

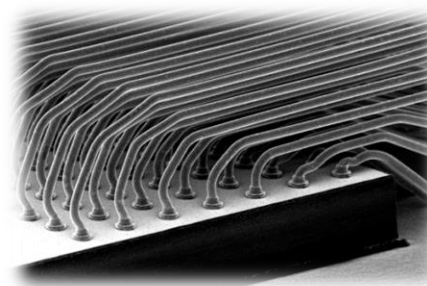


〔新川テクノロジーズ〕

Large variety of test bonding and trial production will be made upon request

<Overview>

- ◆ Accommodate to Au wire 18 $\mu\text{m}\Phi$ ~38 $\mu\text{m}\Phi$
 - ※ Need to discuss except for above wire diameter
 - ※ Need to discuss about Cu and Ag wire
- ◆ Model : UTC-3000
 - ※ Using other old models will be discussed
- ◆ Inspection items will be discussed
- ◆ Test bonding by using the latest version wire bonder will be conducted by Shinkawa LTD.



Please feel free to contact us

Reception Time : Weekday 09:00~ 17:00 (Japan Time)

Phone : +81-42-560-0123

E-mail : skwt-ser@ymrh.co.jp

Basic Contents of Test Bonding

Items	Contents	Remarks
Making Product Type Data	Flame, Magazine, Wiring	
Putting on Conversion Kit for Product Type	Window clammer, Heaterblock	Making conversion-kit for product type will be charged.
Adjustment of Wirebonding	Adjustment of Bonding Parameter	One kind of Product ※ Need to discuss about multi chip product
Measurement Data	Squashed Ball Diameter/Thickness Shear Strength Wire Loop High Wire Pull Strength	Basic "n" number=30 ※ We will change "n" number, depending on product type.
Photograph	◆ External Photograph External view of bonding, After shearing test, After pull test	
Submitting Reports of Final Test Result	We will submit a final reports of test bonding result.	